

SSC8041GS1

P-Channel Enhancement Mode MOSFET

> Features

| V _{DS} | V _{GS} | R _{DS(ON)} Typ. | l _D |
|-----------------|-----------------|--------------------------|----------------|
| -40V | ±20V | 11mΩ@-10V | -20A |
| | | 18mΩ@-4V5 | -20/4 |

> Description

This SSC8041GS1 uses advanced trench technology to provide excellent RDSON and low gate charge. The complementary MOSFETS may be used to form a level shifted high side switch, and for a host of other applications.

100% UIS + ΔVDS + Rg Tested!

Applications

- Load Switch
- PWM Application
- Power Management

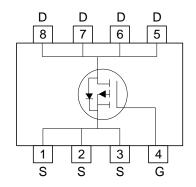
Ordering Information

| Device | Package | Shipping | | |
|------------|---------|-----------|--|--|
| SSC8041GS1 | SOP-8 | 4000/Reel | | |

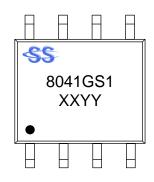
Pin configuration



SOP-8 (Top View)



Pin Configuration



Marking

(XXYY: Internal Traceability Code)



➤ Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

| Symbol | Parameter | Ratings | Unit | | |
|------------------|--|-----------------------|---------|------------|--|
| V_{DSS} | Drain-to-Source Voltage | | -40 | V | |
| V _{GSS} | Gate-to-Source Voltage | | ±20 | V | |
| | Continuous Dunin Comment d | T _C =25°C | -20 | ۸ | |
| l _D | Continuous Drain Current d | T _C =100°C | -10 | А | |
| | Continuous Drain Current ^a | T _A =25°C | -13 | Δ. | |
| IDSM | | T _A =70°C | -9.8 | A | |
| I _{DM} | Pulsed Drain Current b | | -70 | А | |
| <u> </u> | Power Dissipation ^c | Tc=25°C | 5.7 | 10/ | |
| P _D | | T _C =100°C | 2.3 | W | |
| D | Power Dissipation ^a | T _A =25°C | 3.1 | 10/ | |
| P _{DSM} | | T _A =70°C | 2 | W | |
| I _{AS} | Avalanche Current b L=0.5mH Single Pulse | | -15 | А | |
| Eas | Avalanche Energy ^b L=0.5mH Single Pulse | | 56.25 | mJ | |
| TJ | Operation junction temperature | | -55~150 | $^{\circ}$ | |
| Тѕтс | Storage temperature range | | -55~150 | | |

➤ Thermal Resistance Ratings (T_A=25°C unless otherwise noted)

| Symb | ol Parameter | Ratings | Unit |
|------|--|---------|------|
| ReJA | Junction-to-Ambient Thermal Resistance a | 40 | °C/W |

Note:

- a. The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with T_A =25 °C. The value in any given application depends on the user is specific board design. The power dissipation is based on the t≤10s thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation P_D is based on T_{J(MAX)}=150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- d. The maximum current rating is package limited.

SSC-V1.1 www.sscsemi.com Analog Future



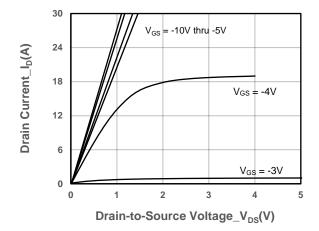


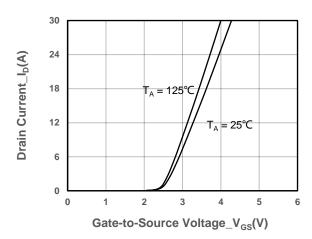
\succ Electrical Characteristics (T_A=25°C unless otherwise noted)

| Parameter | Symbol | Test Conditions | Min. | Тур. | Max. | Unit |
|---------------------------------|----------------------|---|------|------|------|------|
| Drain-Source Breakdown Voltage | V _{(BR)DSS} | $V_{GS} = 0V, I_{D} = -250\mu A$ | -40 | | | V |
| Gate Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}, I_{D} = -250uA$ | -1.2 | -2.2 | -3 | V |
| Drain-Source On-Resistance | R _{DS(on)} | V _{GS} = -10V, I _D = -15A | | 11 | 14 | mΩ |
| Drain-Source On-Resistance | | V _{GS} = -4.5V, I _D = -10A | | 18 | 23 | |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} = -40V, V _{GS} = 0V | | | 1 | μA |
| Gate-Source Leak Current | Igss | $V_{GS} = \pm 20V, V_{DS} = 0V$ | | | ±100 | nA |
| Forward Voltage | V_{SD} | V _{GS} = 0V, I _S = -5A | | -0.7 | -1.3 | V |
| Gate Resistance | R _G | V _{DS} = 0V, f = 1MHz | | 8 | | Ω |
| Input Capacitance | Ciss | V 20V V 0V | | 2650 | | |
| Output Capacitance | Coss | $V_{DS} = -20V$, $V_{GS} = 0V$, $f = 1MHz$ | | 240 | | pF |
| Reverse Transfer Capacitance | C _{RSS} | I = IIVIDZ | | 220 | | |
| Total Gate Charge | Q _G | V 40V V 20V | | 35 | | nC |
| Gate to Source Charge | Q _{GS} | $V_{GS} = -10V, V_{DS} = -20V,$ $I_{D} = -10A$ | | 6 | | |
| Gate to Drain Charge | Q _{GD} | ID = -10A | | 12 | | |
| Turn-on Delay Time | T _{D(ON)} | | | 12 | | |
| Rise Time | Tr | V _{GS} = -20V, V _{DS} = -10V, | | 40 | | |
| Turn-off Delay Time | T _{D(OFF)} | $R_L = 2\Omega, R_G = 6\Omega$ | | 50 | | ns |
| Fall Time | T _f | | | 20 | | |
| Diode Recovery Time | Trr | I _F =-20A, di/dt=500A/us | | 20 | | ns |
| Diode Recovery Charge | Qrr | I _F =-20A, di/dt=500A/us | | 18 | | nC |



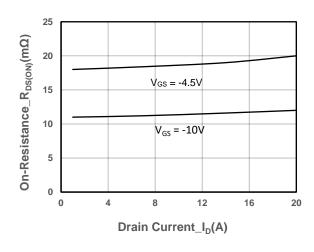
\triangleright Typical Performance Characteristics (T_A=25°C unless otherwise noted)

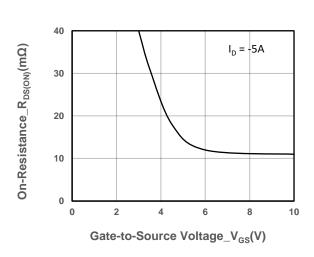




Output Characteristics

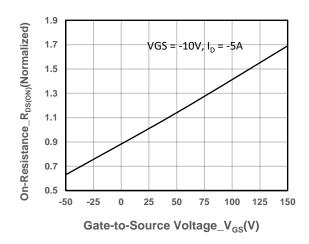
Transfer Characteristics

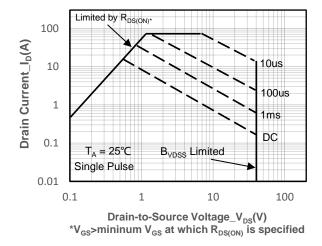




On-Resistance vs. Drain Current and Gate Voltag

On-Resistance vs. Gate-to-Source Voltage



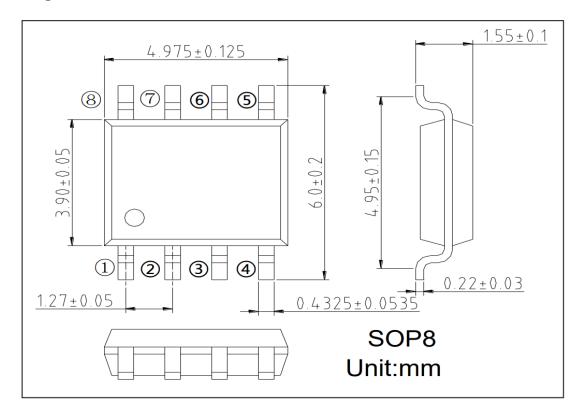


On-Resistance vs. Junction Temperature

Safe Operating Area vs. Junction-to-Ambient



Package Information



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5 / 5